

XPort6173

**Not Recommended
for New Designs**

3U VPX Carrier for Two 2.5 in. Solid-State Drives (SSDs)

Please see XPort6175

- ▶ 3U VPX (VITA 46) module
- ▶ Supports up to two 2.5 in. Solid-State Drives (SSDs)
- ▶ 0.8 in. or 1.0 in. VPX slot pitch
- ▶ Compatible with multiple VITA 65 OpenVPX™ slot profiles
- ▶ x2 PCI Express Gen2 interface
- ▶ Up to 4 TB of storage in MLC-based flash configurations
- ▶ Up to 1 TB in SLC-based flash configurations



XPort6173

The XPort6173 supports two, standard, 2.5 in. Solid-State Drives (SSDs) in a single 0.8 in. or 1.0 in. 3U VPX slot. It provides system integrators quick and easy access to the latest high-density SSD options in a rugged, compact, COTS package. The XPort6173's design mitigates life cycle issues that plague other flash-based storage solutions.

The XPort6173 supports a x2 PCI Express 2.0 interface to the backplane for flexible system connectivity options. Standard configurations of up to 4 TB are available. These modules have been tested and utilize the latest high-density SLC- and MLC-based flash solutions.

X-ES

Extreme Engineering Solutions

...Always Fast

Extreme Engineering Solutions

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VPX (VITA 46) I/O

- x2 PCI Express Gen2 to P1

Storage Characteristics

- Supports up to two ruggedized and shop-replaceable 2.5 in. Solid-State Drives (SSDs)
- Serial ATA (SATA) 6 Gb/s
- Can be used as a bootable drive

Predefined Configurations

- 256 GB of MLC-based flash storage in one drive
- 512 GB of MLC-based flash storage in one drive
- 1 TB of MLC-based flash storage in one drive
- 2 TB of MLC-based flash storage in one drive
- 4 TB of MLC-based flash storage in two drives
- 512 GB of SLC-based flash storage in one drive
- 1 TB of SLC-based flash storage in one drive

Physical Characteristics

- 3U VPX conduction-cooled form factor
- 0.8 in. or 1.0 in. VPX slot pitch
- Dimensions: 100 mm x 160 mm

Environmental Requirements

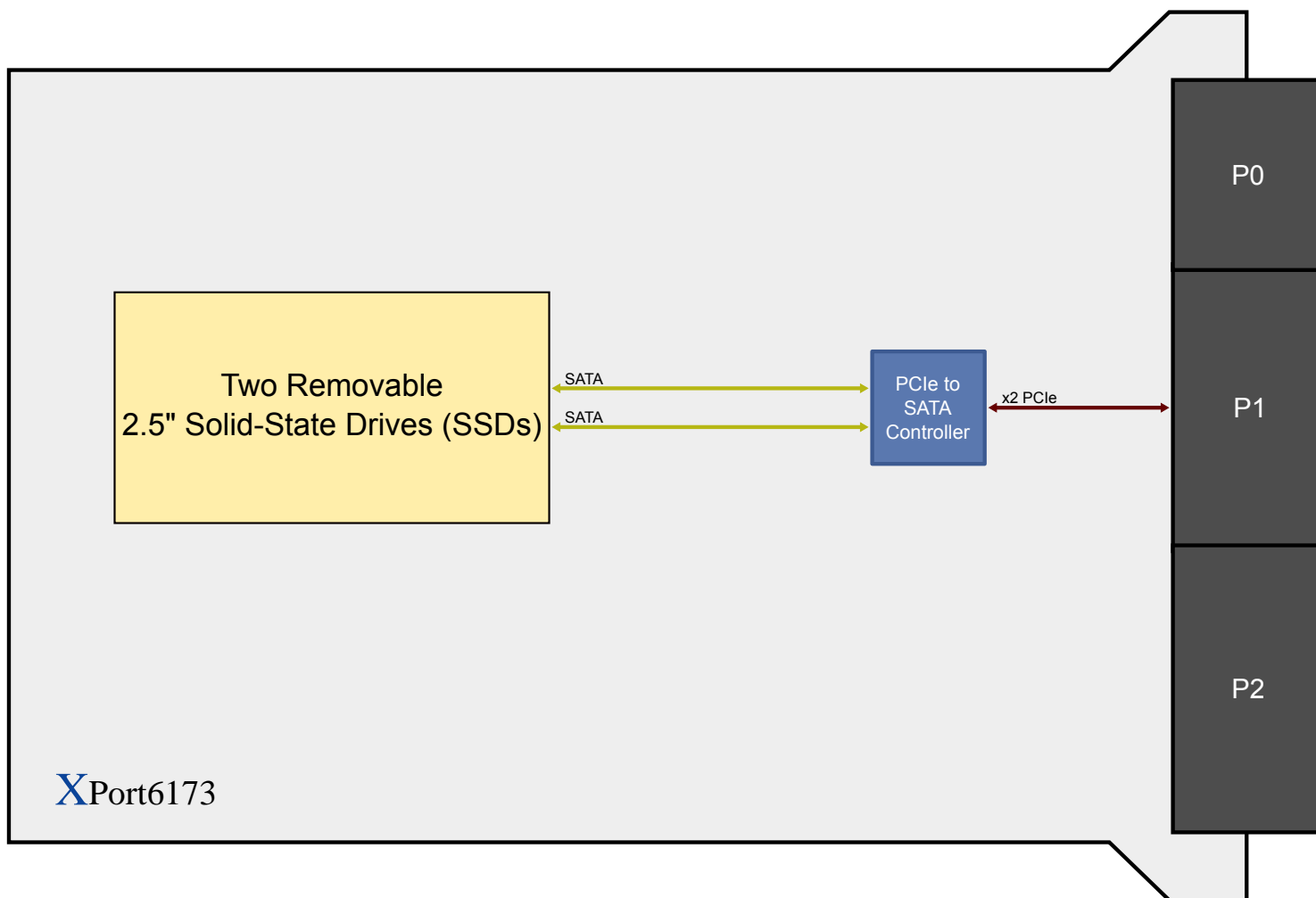
Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 5
- Conformal coating available as an ordering option

Power Requirements

- Power requirements vary depending on SSDs installed. Contact X-ES for additional information.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing



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